

HOSTAFORM® LM90

Laser markable, standard grade

Hostaform® LM90 is a nominal 9 melt flow rate acetal copolymer which is capable of being permanently marked by a laser. Parts molded from Hostaform® LM90 can be laser marked with barcodes, identification numbers, designs, 2-D symbology, etc.

Rheological properties

Melt volume-flow rate	8 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile Modulus	2750 MPa	ISO 527-1/-2
Yield stress, 50mm/min	64 MPa	ISO 527-1/-2
Yield strain, 50mm/min	9 %	ISO 527-1/-2
Flexural Modulus	2700 MPa	ISO 178
Charpy notched impact strength, 23°C	5.5 kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C	5.2 kJ/m ²	ISO 180/1A

Thermal properties

Melting temperature, 10°C/min	167 °C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	98 °C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	161 °C	ISO 306
Coeff. of linear therm. expansion, parallel	100 E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	110 E-6/K	ISO 11359-1/-2

Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.75 %	Sim. to ISO 62
Density	1410 kg/m ³	ISO 1183

Injection

Drying Temperature	100 - 120 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Max. mould temperature	80 - 120 °C
Back pressure	4 MPa
Injection speed	slow-medium

Additional information

Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.
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Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Processing Texts

Pre-drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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Injection molding Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hygroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3 hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Injection molding Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be

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necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.

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